

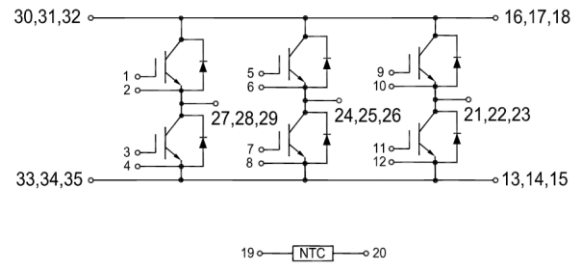


SYMT200FF120T6H-M

IGBT Module

Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated > 10μs
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2×I_C)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



Applications:

- Industrial Inverters
- Servo Applications

IGBT, Inverter

Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage	T _J =25°C	1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _C	Continuous Collector Current	T _C =100°C	200	A
		T _C =25°C	385	A
I _{CM}	Peak Collector Current Repetitive	t _p =1 ms	400	A
t _{SC}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation (IGBT)	T _C =25°C T _{Jmax} =175°C	1305	W



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 3\text{mA}$, $V_{CE} = V_{GE}$	5.0	5.6	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 200\text{A}$, $V_{GE} = 15\text{V}$	$T_J=25^\circ\text{C}$	1.70		V
			$T_J=125^\circ\text{C}$	1.90		V
			$T_J=150^\circ\text{C}$	2.00		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE} = 0\text{V}$, $V_{CE} = V_{CES}$, $T_J = 25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{V}$, $V_{CE} = V_{CES}$, $T_J = 25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE} = 25\text{V}$, $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$		17		nF
C_{res}	Reveres Transfer Capacitance			0.57		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600\text{V}$, $I_C = 200\text{A}$, $R_{Gon} = 1\Omega$, $V_{GE} = \pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	254		ns
			$T_J=125^\circ\text{C}$	260		
			$T_J=150^\circ\text{C}$	266		
t_r	Rise Time		$T_J=25^\circ\text{C}$	87		ns
			$T_J=125^\circ\text{C}$	92		
			$T_J=150^\circ\text{C}$	95		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$	252		ns
			$T_J=125^\circ\text{C}$	281		
			$T_J=150^\circ\text{C}$	289		
t_f	Fall Time	$T_J=25^\circ\text{C}$	155		ns	
		$T_J=125^\circ\text{C}$	199			
		$T_J=150^\circ\text{C}$	226			
E_{on}	Turn-on Switching Loss	$V_{CC} = 600\text{V}$, $I_C = 200\text{A}$, $R_{Gon} = 1\Omega$, $V_{GE} = \pm 15\text{V}$, $di/dt = 1851\text{A}/\mu\text{s}$ ($T_J=150^\circ\text{C}$) Inductive Load	$T_J=25^\circ\text{C}$	8.4		mJ
		$T_J=125^\circ\text{C}$	12.9			
		$T_J=150^\circ\text{C}$	14.2			



E _{off}	Turn-off Switching Loss	V _{CC} = 600V, I _C = 200A, R _{Goff} = 1Ω, V _{GE} = ±15V, du/dt = 4407V/μs (T _J = 150°C) Inductive Load	T _J = 25°C	11.7	mJ
			T _J = 125°C	19.3	
			T _J = 150°C	21.5	
Q _g	Total Gate Charge	V _{GE} = -15...+15V	T _J = 25°C	960	nC
R _{g internal}	Internal Gate Resistance		T _J = 25°C	3.3	Ω
RBSOA	I _C = 400A, V _{CC} = 1050V, V _p = 1200V, R _G = 1Ω, V _{GE} = +15V to 0V, T _J = 150°C		Trapezoid		
I _{SC}	SC Data	V _{CC} = 600V, t _p = 10μs, V _{GE} = ±15V, R _{Gon} = 4.7ohm, R _{Goff} = 4.7ohm, T _J = 150°C		1044	A
R _{θJC}	IGBT Thermal Resistance: Junction-To-Case			0.115	°C/W

Diode, Inverter

Maximum Rated Values (T_C = 25°C unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	T _J = 25°C	1200	V
I _F	Diode Continuous Forward Current		200	A
I _{FM}	Peak FWD Current Repetitive	t _p = 1ms	400	A

Electrical Characteristics of FWD (T_C = 25°C unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit
V _{FM}	Forward Voltage	I _F = 200A	T _J = 25°C	1.80		V
			T _J = 150°C	1.95		
t _{rr}	Reverse Recovery Time	I _F = 200A, -di _F /dt = 1300A/μs (T _J = 150°C), V _R = 600V, V _{GE} = -15V	T _J = 25°C	286		ns
			T _J = 125°C	456		
			T _J = 150°C	522		
I _{rr}	Peak Reverse Recovery Current	I _F = 200A, -di _F /dt = 1300A/μs (T _J = 150°C), V _R = 600V, V _{GE} = -15V	T _J = 25°C	145		A
			T _J = 125°C	172		
			T _J = 150°C	178		
Q _{rr}	Reverse Recovery Charge	I _F = 200A, -di _F /dt = 1300A/μs (T _J = 125°C), V _R = 600V, V _{GE} = -15V	T _J = 25°C	21.4		μC
			T _J = 125°C	35.8		
			T _J = 150°C	41.3		



E _{rec}	Reverse Recovery Energy	T _J =25°C	10.2	mJ
		T _J =125°C	17.2	
		T _J =150°C	19.7	
R _{θJC}	Diode Thermal Resistance: Junction-To-Case		0.199	°C/W

Internal NTC-Thermistor Characteristics

Symbol	Description		Min.	Typ.	Max.	Units.
R ₂₅	Rated Resistance	T _C =25°C		5		kΩ
ΔR/R	Deviation of R100	T _C =100°C, R ₁₀₀ =481Ω	-5		5	%
P ₂₅	Power Dissipation	T _C =25°C			10	mW
B _{25/50}	B-Value	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3380		K
B _{25/80}	B-Value	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3440		K
B _{25/100}	B-Value	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$		3545		K

Module

Symbol	Description	Conditions	Min	Typ	Max	Unit
V _{iso}	Isolation Voltage (All Terminals Shorted)	RMS, f=50Hz, 1minute	2500			V
L _{sCE}	Stray Inductance Module			21		nH
T _J	Maximum Junction Temperature				175	°C
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+150	°C
T _{stg}	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R _{θCS}	Case-To-Sink Thermally (Conductive Grease Applied)			0.1		°C/W
M	Mounting Torque for Module Mounting	Screw M5--Mounting according to valid application note	3.0		6.0	N·m
G	Weight			300		g

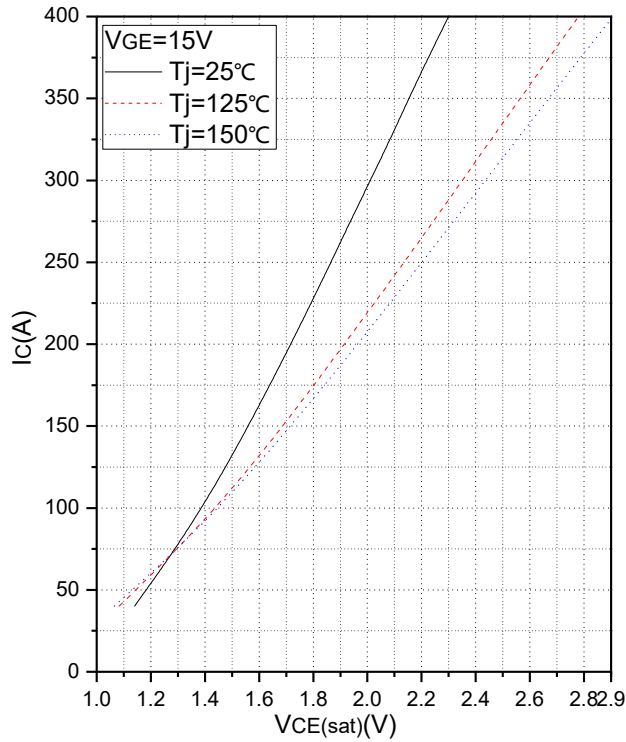


Fig.1 Typical Saturation Voltage Characteristics

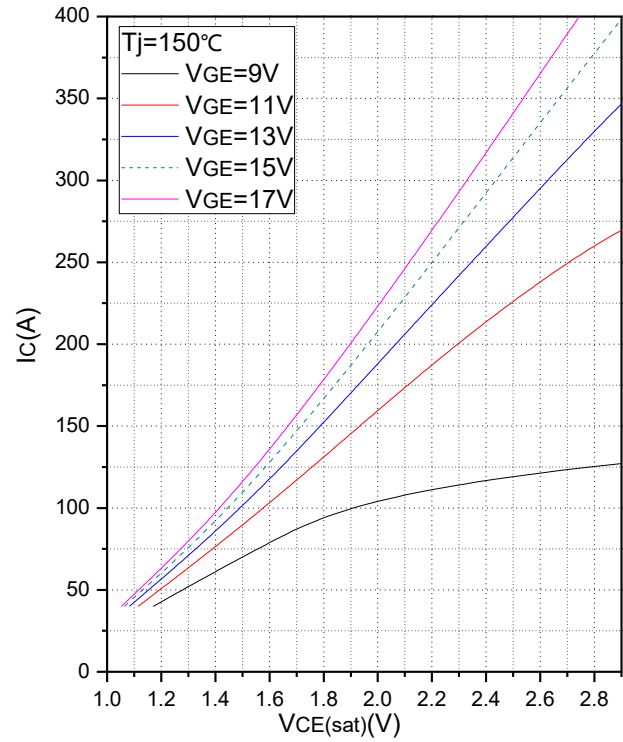


Fig.2 Typical Output Characteristics

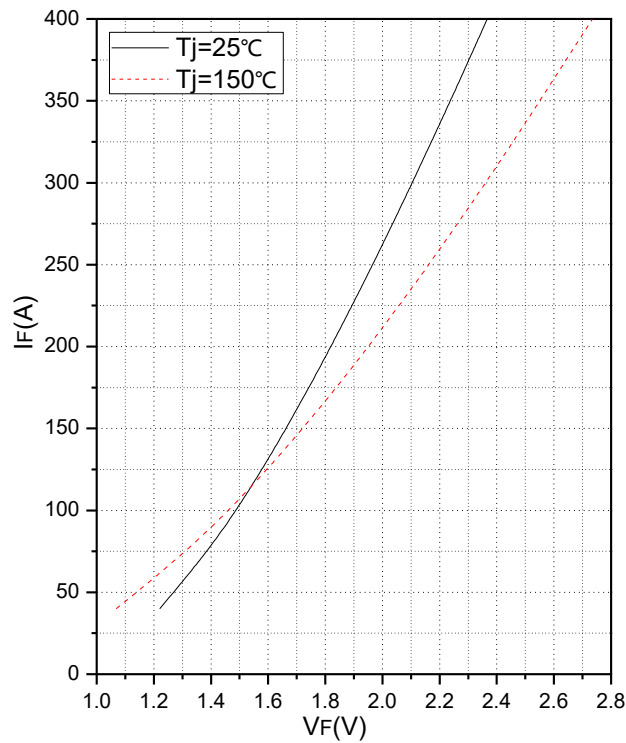


Fig.3 Forward Characteristics of FWD

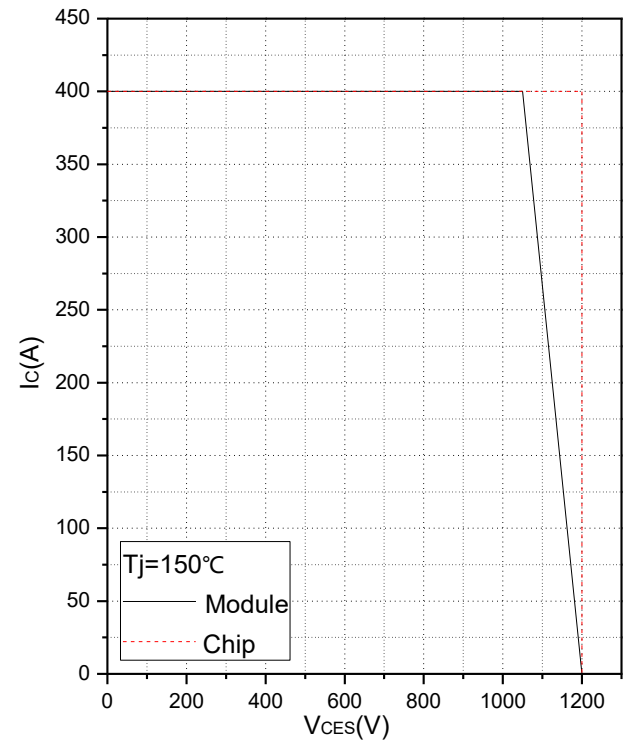


Fig.4 Reverse Bias Safe Operation Area (RBSOA)

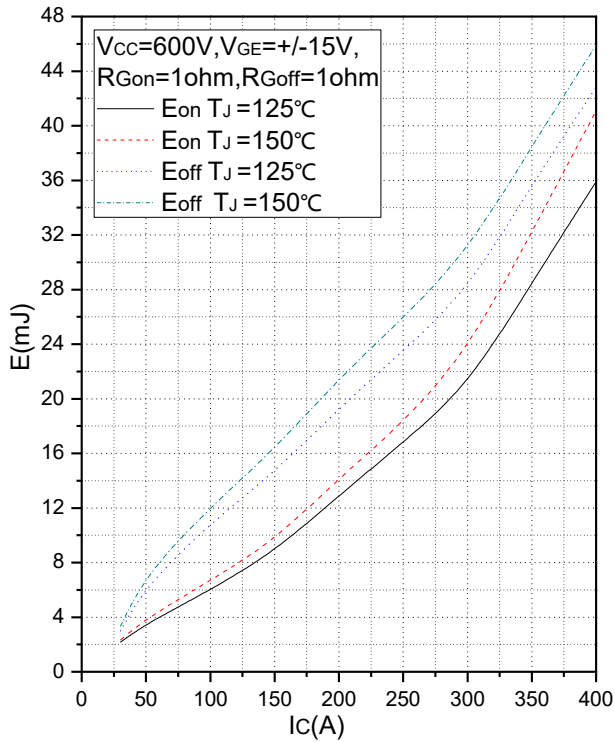


Fig.5 Typical Switching Loss vs. Collector Current

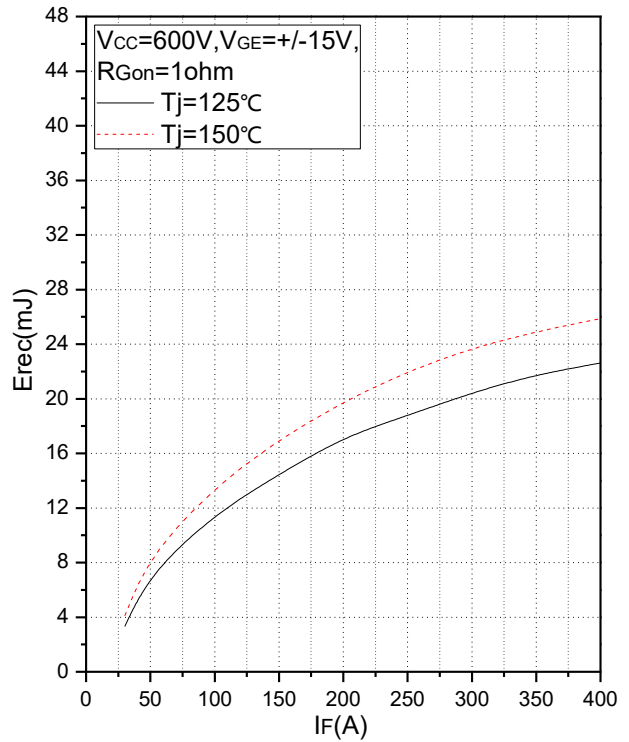


Fig.6 Typical Switching Loss vs. Forward Current

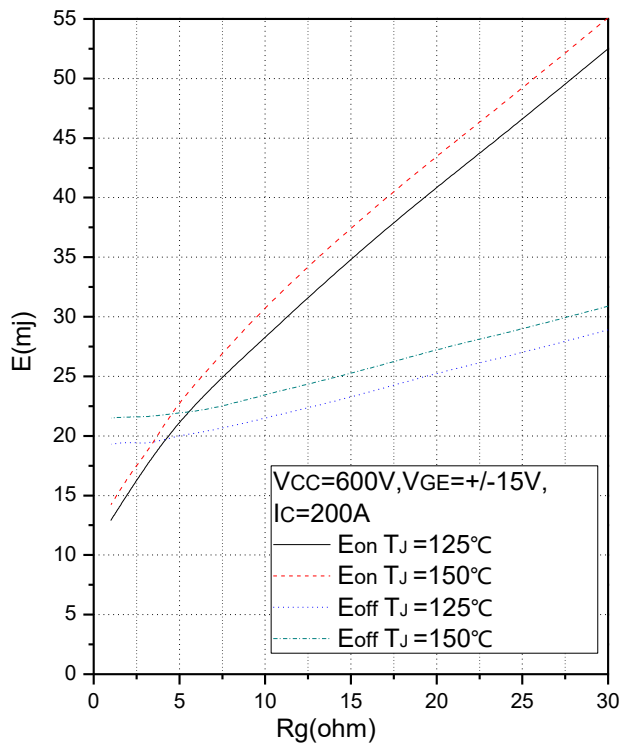


Fig.7 Typical Switching Loss vs. Gate Resistance

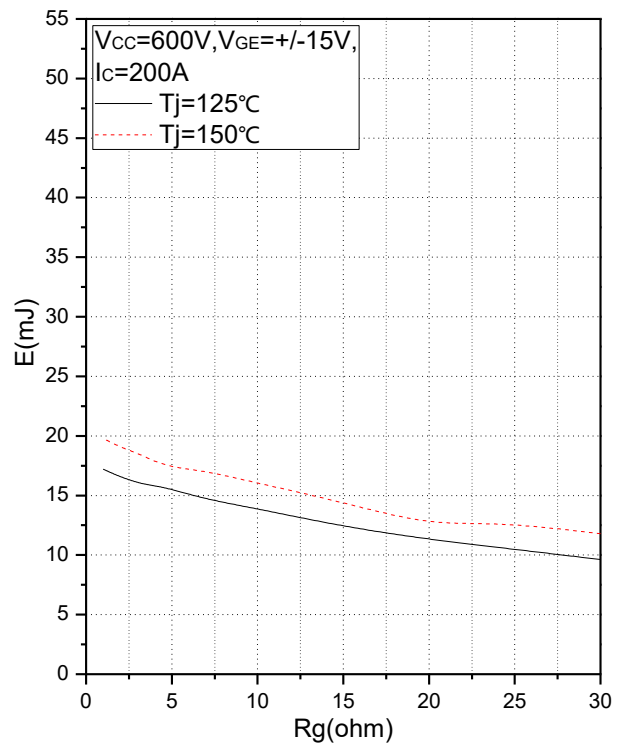


Fig.8 Typical Switching Loss vs. Gate Resistance

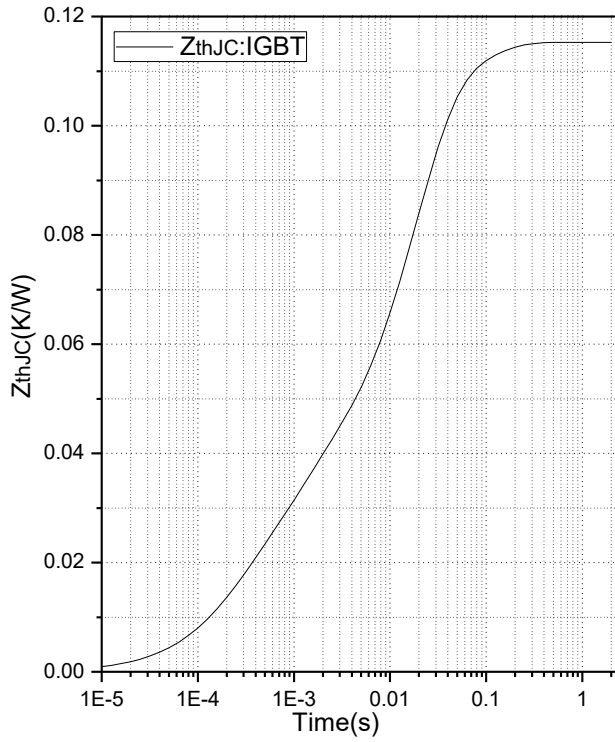


Fig.9 Transient Thermal Impedance (IGBT)

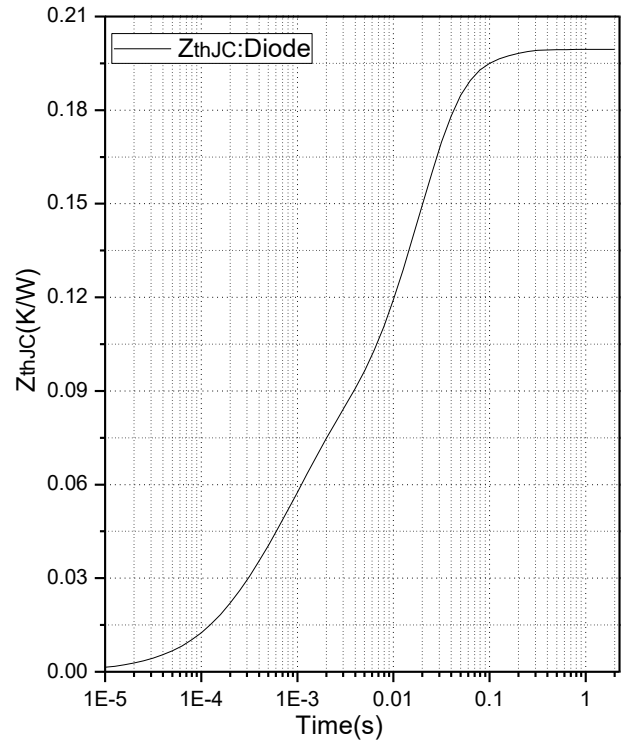


Fig.10 Transient Thermal Impedance (Diode)

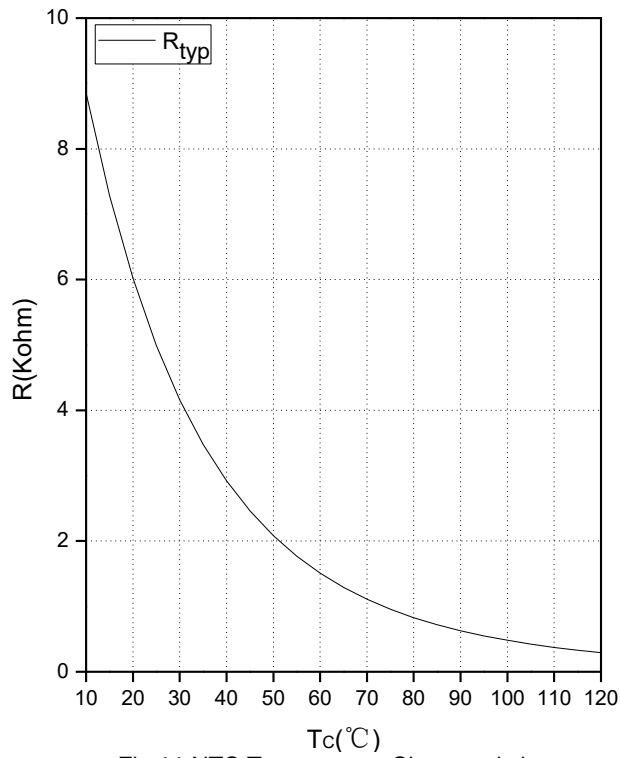
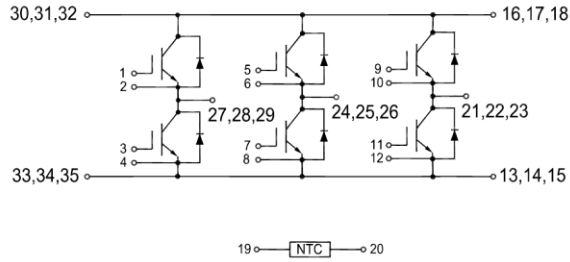
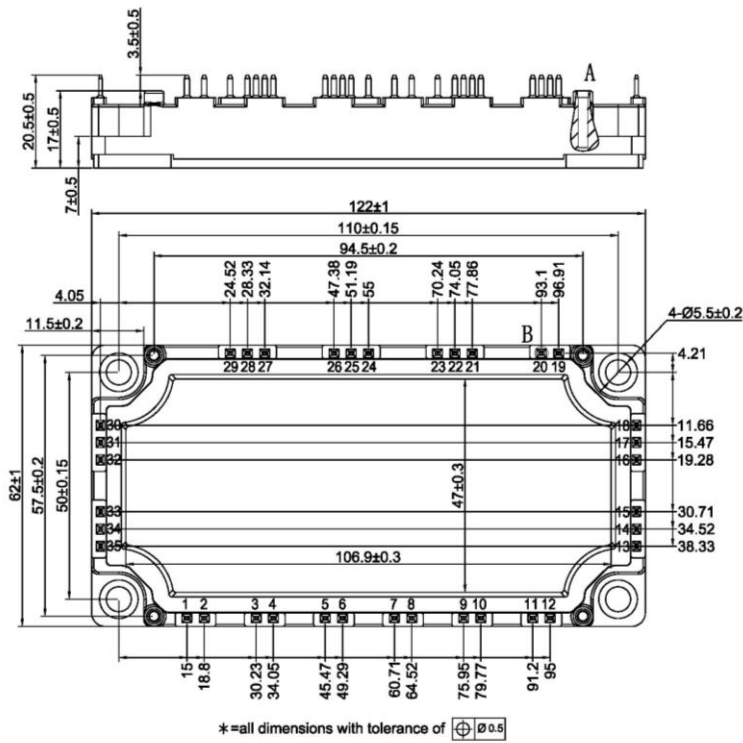


Fig.11 NTC Temperature Characteristics

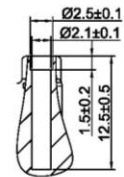
Internal Circuit:



Package Outline (Unit: mm):



View A
scale 3:1



View B
scale 3:1

